



## Material Content Data Sheet



<b>Sales Product Name</b>		IPD50N08S4-13		<b>Issued</b>		19. January 2018		
<b>MA#</b>		MA001619308						
<b>Package</b>		PG-TO252-3-313		<b>Weight*</b>		317.90 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.872	0.59	0.59	5888	5888
leadframe	inorganic material	phosphorus	7723-14-0	0.044	0.01		139	
	non noble metal	iron	7439-89-6	0.147	0.05		463	
	non noble metal	copper	7440-50-8	147.096	46.27	46.33	462719	463321
	non noble metal	aluminium	7429-90-5	2.155	0.68	0.68	6780	6780
wire	non noble metal	aluminium	7429-90-5	2.155	0.68	0.68	6780	6780
encapsulation	organic material	carbon black	1333-86-4	1.404	0.44		4415	
	plastics	epoxy resin	-	24.563	7.73		77268	
	inorganic material	silicondioxide	60676-86-0	114.395	35.98	44.15	359850	441533
leadfinish	non noble metal	tin	7440-31-5	3.740	1.18	1.18	11765	11765
plating	inorganic material	phosphorus	7723-14-0	0.003	0.00		11	
	non noble metal	nickel	7440-02-0	1.421	0.45	0.45	4468	4479
solder	non noble metal	tin	7440-31-5	0.037	0.01		117	
	noble metal	silver	7440-22-4	0.046	0.01		146	
	non noble metal	lead	7439-92-1	1.770	0.56	0.58	5567	5830
heatspreader	inorganic material	phosphorus	7723-14-0	0.006	0.00		18	
	non noble metal	iron	7439-89-6	0.019	0.01		60	
	non noble metal	copper	7440-50-8	19.177	6.03	6.04	60326	60404
*deviation	< 10%		Sum in total:			100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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